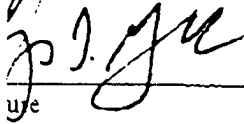


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May 17, 2002

Date

THE UNITED STATES PATENT AND TRADEMARK OFFICE

licant : Andreas Lenniger et al.
ic. No. : 09/436,598
 : November 9, 1999
 : Power Semiconductor Module With Ceramic Substrate
iner : David E. Graybill - Art Unit: 2814

PLEMENTAL RESPONSE

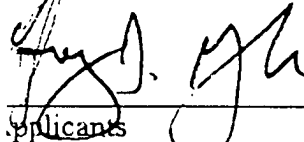
Commissioner of Patents and Trademarks,
ington, D. C. 20231

MAY 17 2002

lemental to the preliminary amendment and the *Request for Continued Examination*
itted on March 4, 2002, enclosed please find an executed Declaration under 37 C.F.R.
to overcome the anticipation rejection of claims 1-7. The declaration specifically
s reference to claim 1 as amended in the aforesaid preliminary amendment. The
tors clearly state in the enclosed Declaration under 37 C.F.R. 1.132 that the inventive
-fit feature is **not inherent** to applicants' admitted prior art.

nsideration of the application and the allowance of claims 1-7 are respectfully solicited.

ectfully submitted,



Applicants

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May 17, 2002
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5/17/02
Date

THE UNITED STATES PATENT AND TRADEMARK OFFICE

licant : Andreas Lenniger et al.
ic. No. : 09/436,598
ed : November 9, 1999
e : Power Semiconductor Module With Ceramic
Substrate
iner : David E. Graybill
p Art Unit : 2814

ARATION in accordance with 37 CFR 1.132

COMMISSIONER OF PATENTS AND TRADEMARKS,
INGTON, DC 20231

MAY 17 2002

order to assist in the prosecution of this application and
traversal of the rejection of the claims by the Examiner,
Dr. Andreas Lenninger, Alfred Kember, and Gottfried
er, do hereby declare as follows:

are citizens of Germany, and we are the named inventors who
the invention of this application.

Andreas Lenninger, am a trained engineer specializing in
electrical engineering. I received the degrees of Dipl.-Ing.
Dr. Ing. at the Ruhr University of Bochum in 1988 and
1991, respectively. Since 1994, I have been employed as a
manager for process engineering.

Andreas Lenninger, am the inventor or a co-inventor of U.S.
Patent No. 5,847,286 among others.

Alfred Kember, am a trained technical manager. Since 1961,
I have been employed as a manager in industrial engineering.

Hottfried Ferber, am a trained technical engineer
specializing in mechanical engineering. Since 1961, I have
been employed as a mechanical designer.

I have read the specification and claims of this application,
the Office action dated August 28, 2000, the response thereto
dated December 29, 2000, the final Office action dated March
2001, and the second final Office action dated December 4,
2001, in which claims 1 to 7 were finally rejected under
Section 102(b) as unpatentable over applicants' admitted prior
art. Arguments explaining why the present claims are believed

define subject matter that is not taught or suggested by prior art are set forth herein.

Discussion

Rejection of Claims 1 to 7 under 35 U.S.C. § 102(b)

Pages 2 to 3 of the above-identified Office action, the Examiner rejected claims 1 to 7 as being fully anticipated by applicants' admitted prior art under 35 U.S.C. § 102. In the § 102 rejection, the Examiner states: "the product of applicant's admitted prior art inherently possesses the characteristics imparted by" the feature "terminals press-fitted into housing element openings." Final Office action at 3.

Applicants disagree with the Examiner and agree with the analysis set forth in the Response filed December 29, 2000, and conclude that the press-fitted feature of the invention of the instant application is not inherent.

Claim 1 calls for, *inter alia*, Claim 1 calls for, *inter alia*, a semiconductor module, including:

semiconductor components;

a plastic housing having an interior and connecting element openings formed therein;

a substrate disposed in the plastic housing defining a housing base of the plastic housing, the substrate containing a ceramic plate having a top side and a bottom side with a top metallization layer disposed on the top side and a bottom metallization layer disposed on the bottom side, the top metallization layer facing the interior of the plastic housing being patterned in order to form interconnects and equipped for and receiving the semiconductor components;

terminal elements for providing external terminals, the terminal elements press-fitted into the connecting element openings in the plastic housing; and

wires bonded to the terminal elements and to the semiconductor components.

have undertaken a thorough review of the specification of instant application and the prior art and state that the notion of the instant application is not inherent to applicants' admitted prior art.

described in the last line of claim 1 and page 7, lines 16
15, of the specification of the instant application, the
er module according to the invention of the instant
lication differs from the prior art in that the terminals
tioned in claim 1 are press-fitted into the openings of the
ing element.

prior art cited in the introductory specification and the
or art references cited by the Examiner each describe power
les in which the terminal pins are injection-molded with a
stic during the production process. The disadvantage
eof is, as described on page 2, lines 1 to 13, of the
ification of the instant application, that the terminal
s and the plastic have different expansion coefficients so
gaps between the plastic and the terminal pins can arise
r the plastic material cools off. Such gaps lead to loose
inal pins. Loose terminal pins is a disadvantage that is
ded with the power module according to the invention of
instant application because the terminal pins of the
ntion are not injection-molded with plastic. Rather, they
"press-fitted into . . . openings" of the power module
ing during production. Such a process is not inherent to
icants' admitted prior art.

reby declare that all statements made herein of my own
ledge are true and that all statements made on information

belief are believed to be true, and further that these
statements were made with the knowledge that willful false
statements and the like so made are punishable by fine or
imprisonment or both, under Section 1001 of Title 18 of the
United States Code and that such willful false statements may
vitiolate the validity of the application or any patent
issued thereon.

30-04-2002
Sed: Lyns
Dr. Andreas Lenninger

02-05-2002
Sed: Alfred Kember
Alfred Kember

03.05.2002
Sed: Ferber
Gottfried Ferber

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